Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HPE 12900E 36p 100GbE QSFP28 HB Mod (JH357A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardantsweighing> 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#
Socket spanner	M3

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the film 1, film 2 and part 3;
2. Unscrew the screws on part 4,and then remove part 4;
3. Unscrew the screws on part 5,and then remove part 5;
4. Unscrew the screws on part 6,and then remove part 6;
5. Remove the film 4-1 and part 4-2 from part 4;
6. Remove the part 6-1 from part 6;
7. Unscrew the screws on pcb 7,and then remove pcb 7;
8. Unscrew the screws on heatsink 8,and then remove heatsink 8;
9. Unscrew part 9,and then remove part 9;
10. Unscrew part 10,and then remove part 10;
11. Push part 7-3,and then remove part 7-1 and part 7-2 from pcb 7;
12. Push part 7-3,and then remove heatsink 11-1 and heatsink 11-2 from pcb 11;
13. Unscrew the screws on pcb 11,and then remove part 11-3 and part 11-4 from pcb 11;
14. Remove the film 12-1 from part 12;

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

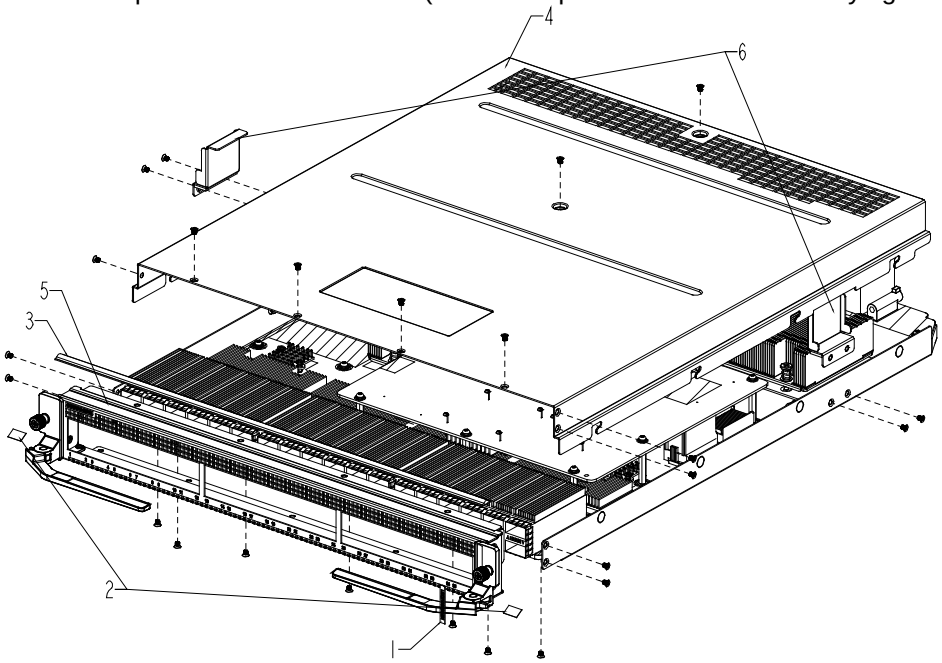

Figure 1 Treatments to the product

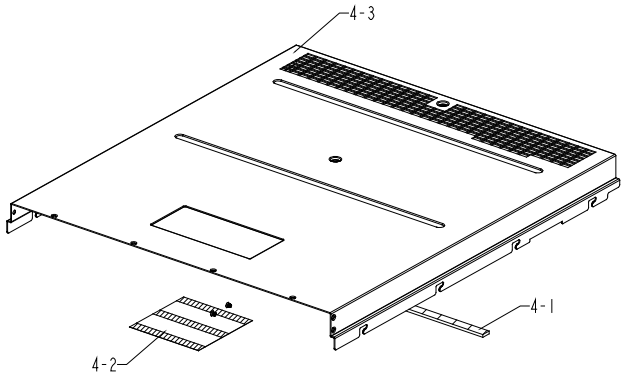

Figure 2 Treatments to part 4

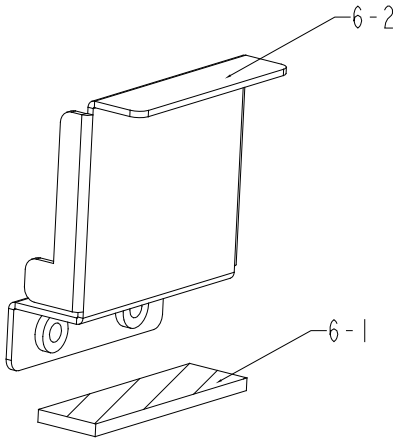

Figure 3 Treatments to part 6

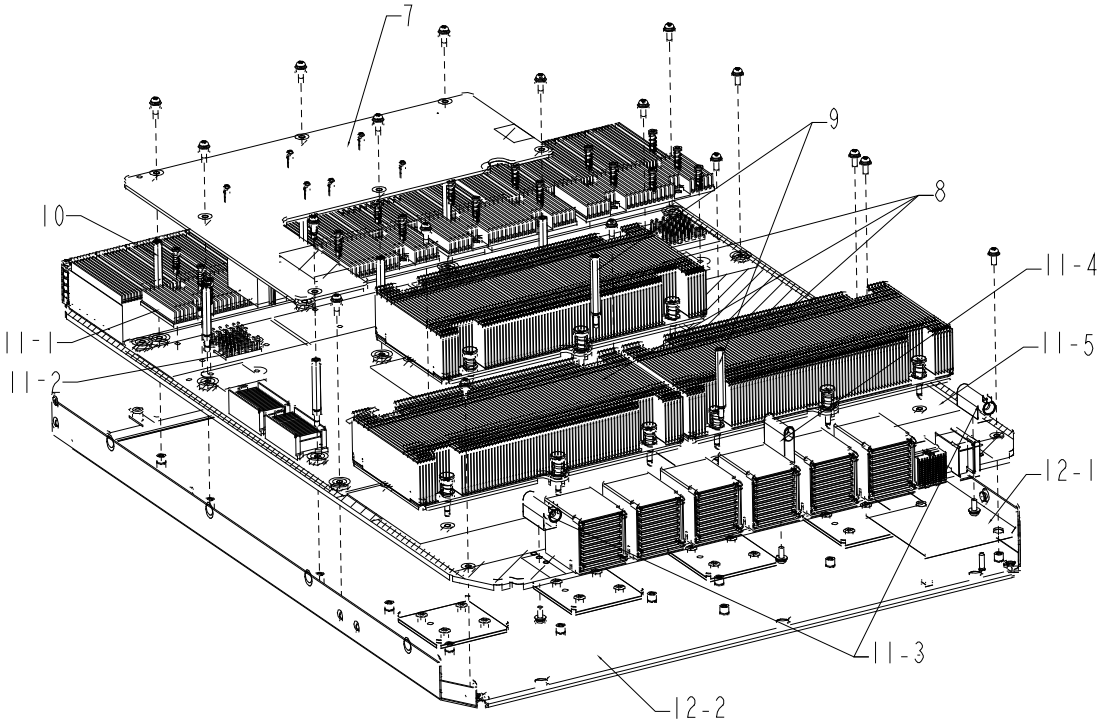

Figure 4 Treatments to the product

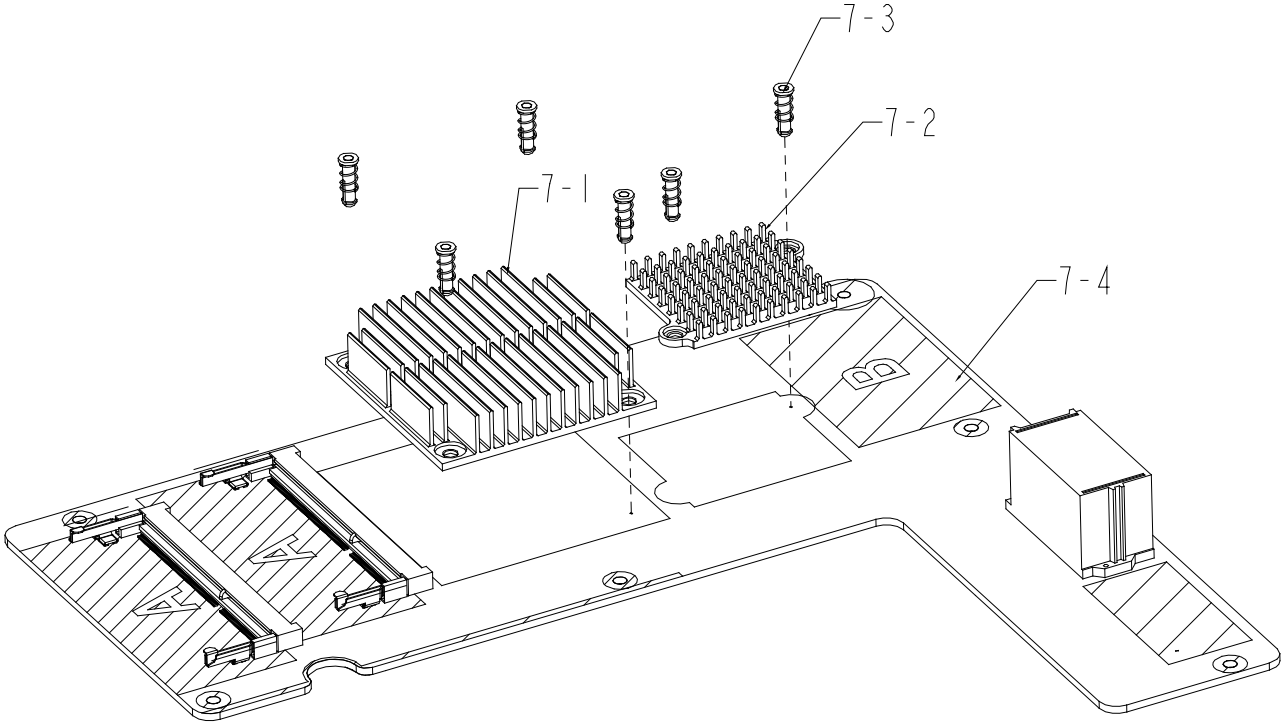

Figure 5 Treatments to pcb 7

3.3 Material of the facility built

Facility	Components	Material	Weight(g) *PCS	Weight percentage	Selective treatment for materials and components	Details
3		Pla	3*1	0.03%		Pla recycling
4						
	4-1	Pla	1*1	0.01%		Pla recycling
	4-3	Fe	1587*1	15.04%		Fe recycling
5		Fe ,Zn	472*1	4.47%		Fe, Zn recycling
6						
	6-2	Fe	23*2	0.44%		Fe recycling
7						
	7-1	Al	42*1	0.40%		Al recycling
	7-2	Al	9*1	0.09%		Al recycling
	7-3	Pla, Fe	1*24	0.23%		Pla, Fe recycling
	7-4	Complex PCB	248*1	2.35%	The surface of PCB is greater than 10 square centimeters;	
8		Fe, Cu	1098*3	31.23%		Fe, Cu recycling
9		Fe	6*2	0.11%		Fe recycling
10		Fe	5*7	0.33%		Fe recycling
11						
	11-1	Al	41*4	1.55%		Al recycling
	11-2	Al	3*2	0.06%		Al recycling
	11-3	Zn	16*2	0.30%		Zn recycling
	11-4	Zn	23*1	0.22%		Zn recycling
	11-5	Complex PCB	2765*1	26.21%	The surface of PCB is greater than 10 square centimeters;	
12						
	12-2	Fe, Al	1786*1	16.93%		Fe, Al recycling

4. Revised record

Date	Version	Author	Modify content
2016.03.28	V0	Chen Linwei	Initial version
2016.04.28	V1	Chen Linwei	Add part “0231A4X4”